

Power Train Scaling for High Frequency Switching, Impact on Power Controller Design

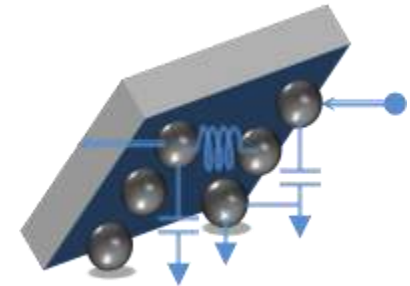
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Oct 2010

IEEE PowerSoC 2010

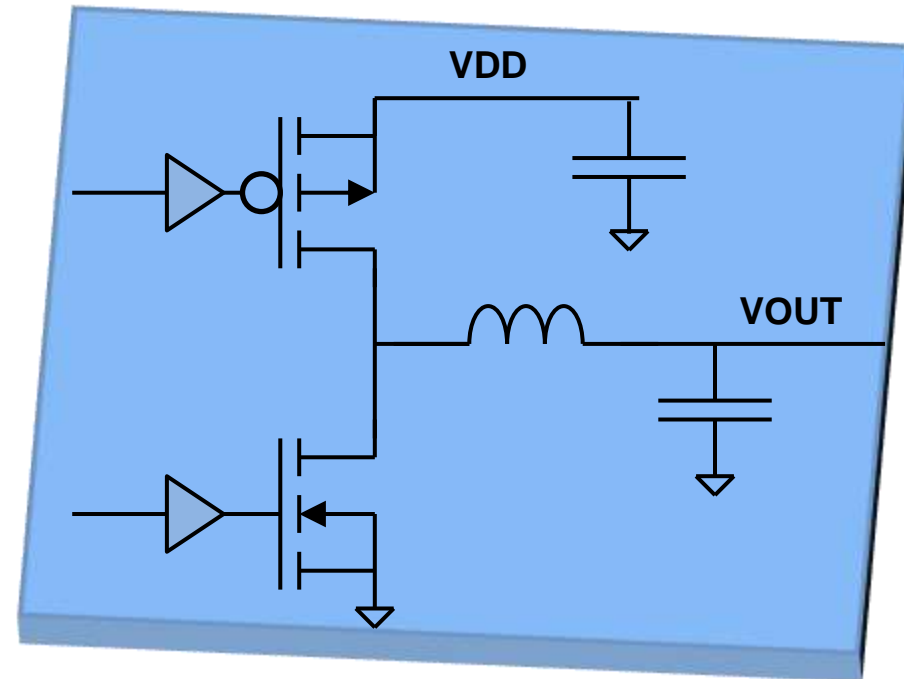
Outline

- **Background for High Frequency Switching**
- **Dealing with Noise**
- **Challenges For HF Controllers**

HF DC to DC Converters

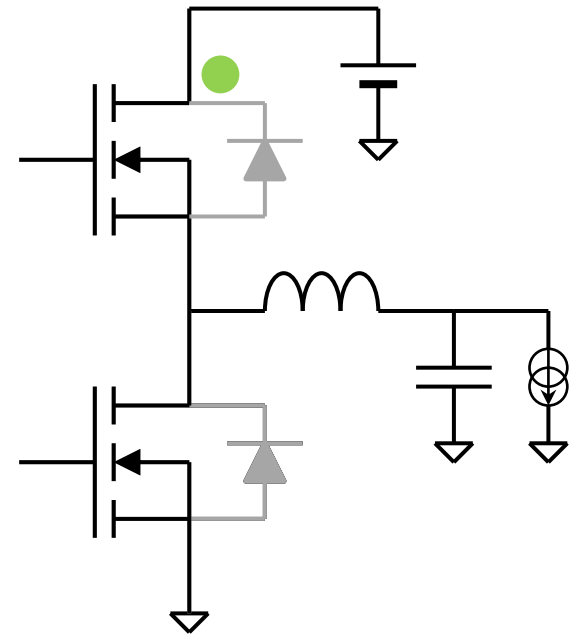
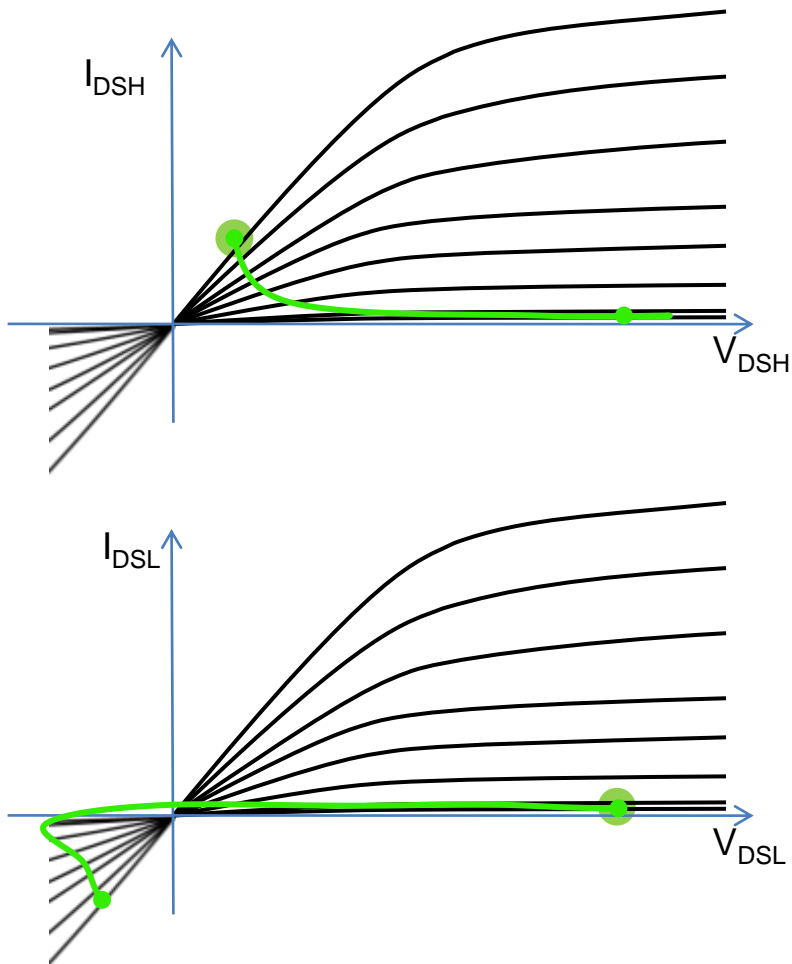
Challenges

- **Challenges for Technologist**
 - Ultra Fast Power Switches with High Breakdown Voltage
 - Low DCR HF Inductor
 - Low ESR Capacitor
 - **Compatible Integration Process**
 - SiP, SoC etc
- **Challenge for Designers**
 - Voltage ringing is way higher than regulated voltage amplitude
 - Differentiate Load transients from Ringing
 - Power Consumption in PWM circuitry
 - **Construct Simple, Scalable and Exportable Design**
- **Only Simple Ideas work efficiently**



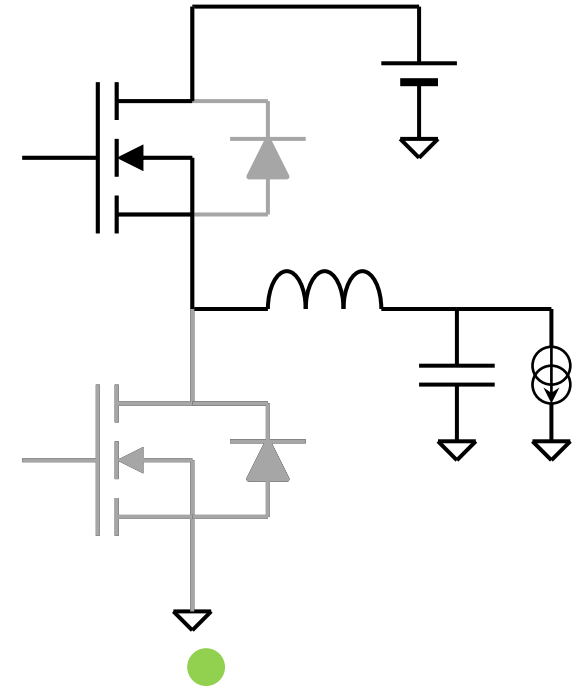
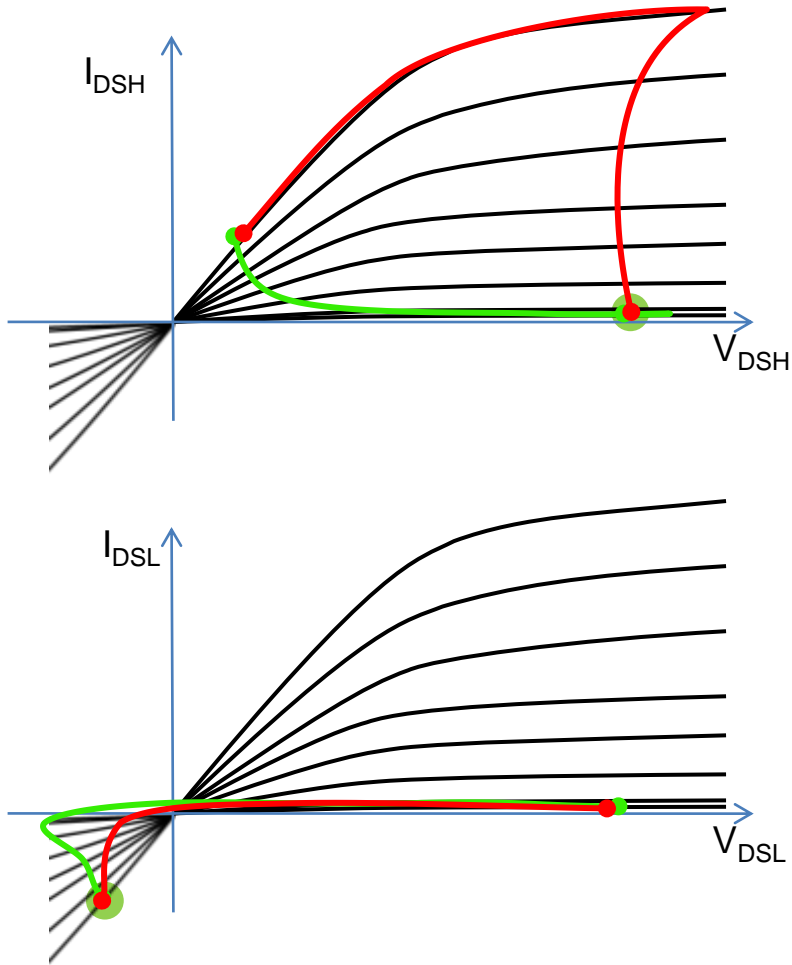
Background, Solid State Power Switching

Hi-Lo Transition



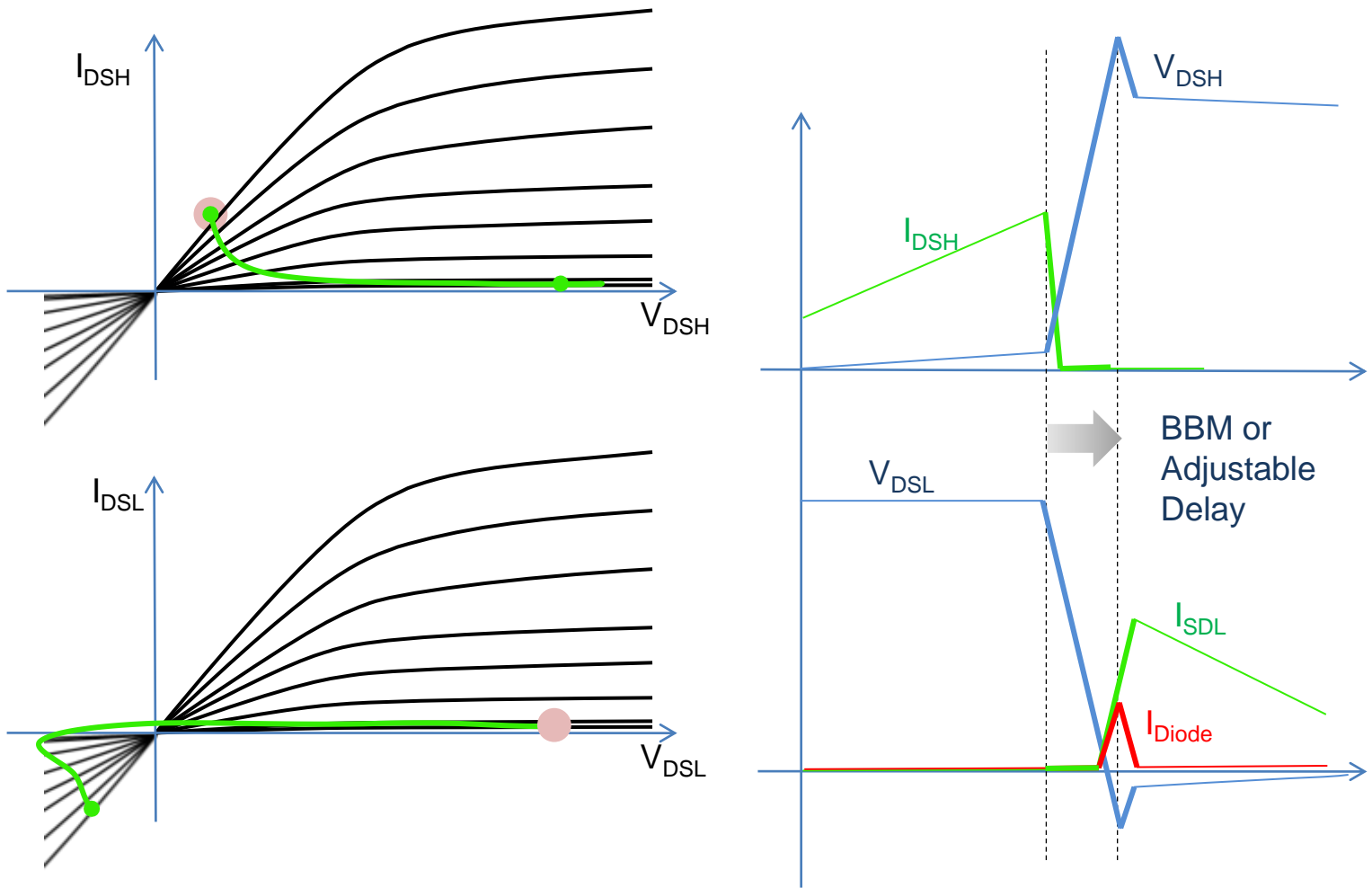
Background, Solid State Power Switching

Lo-Hi Transition



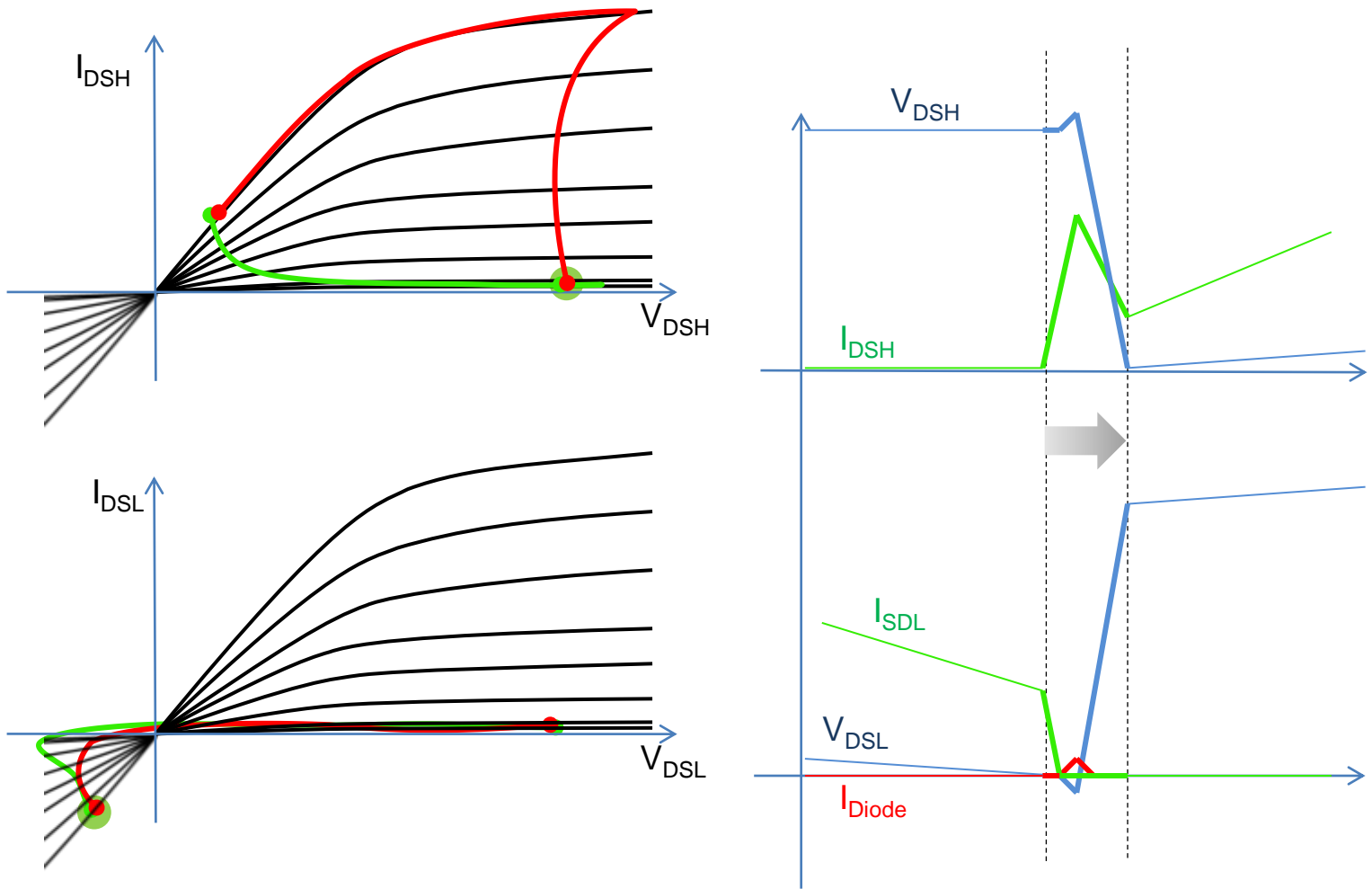
Background, Solid State Power Switching

Hi-Lo Transition : Waveforms



Background, Solid State Power Switching

Lo-Hi Transition : Waveforms



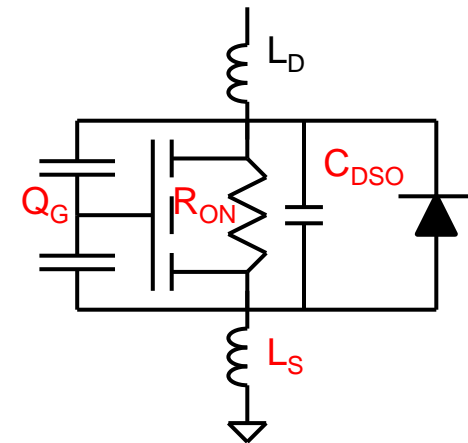
Overview of Switch Power Losses

Low Side Switch

- **Switching Losses Causes**

- Q_G Charging and discharging
- C_{DS} Charging (Discharging is often adiabatic)
- Body diode charge recovery (losses induced at HS switch)
- Parasitic Inductor Energy

$$P_{AC} = \frac{1}{T_0} \left(\frac{1}{2} C_{DSO} V_{DD}^2 + Q_G V_{DD} + Q_R V_{DD} + \frac{1}{2} L_S I_L^2 \right)$$



- **Conduction Losses**

- Conduction losses in R_{DSON}
- Body diode Forward losses (short time)
- Shoot through current (use BBM)

$$P_{DC} = (1 - D) \cdot R_{ON} \cdot I_L^2 + (1 - D) \cdot R_{ON} \cdot \frac{\Delta I^2}{12} + \frac{\Delta T}{T_0} \cdot V_F \cdot I_L$$

Overview of Switch Power Losses

High Side Switch

- **Switching Losses Causes**

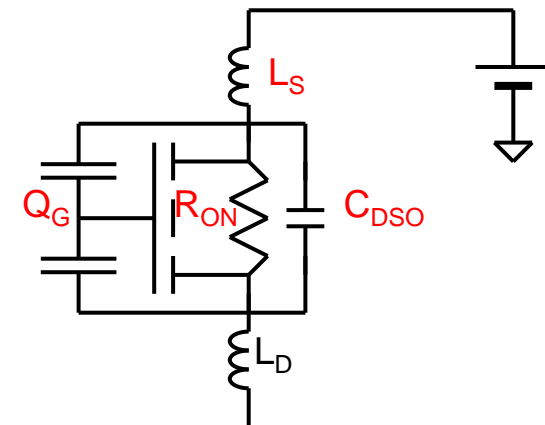
- Q_g Charging and discharging
- C_{DS} Discharging (Charging is often adiabatic)
- $I_{ds} \times V_{ds}$ crossing at turn on
- Parasitic Inductor Energy

$$P_{AC} = \frac{1}{T_0} \left(Q_G V_{DD} + \frac{I_L}{I_{DRV}} C_{GDO} \cdot V_{DD}^2 + \frac{1}{2} C_{D50} V_{DD}^2 + \frac{1}{2} L_S I_L^2 \right)$$

- **Conduction Losses**

- Conduction losses in R_{DSON}
- Shoot through current (use BBM)

$$P_{DC} = D \cdot R_{ON} \cdot I_L^2 + D \cdot R_{ON} \cdot \frac{\Delta I^2}{12}$$



Intrinsic Limitations for Power Train Scaling

- The sum ($P_{AC} + P_{DC}$) is minimum When ($P_{AC} = P_{DC}$)
- Reason : $P_{AC} \times P_{DC} = \text{Constant}$

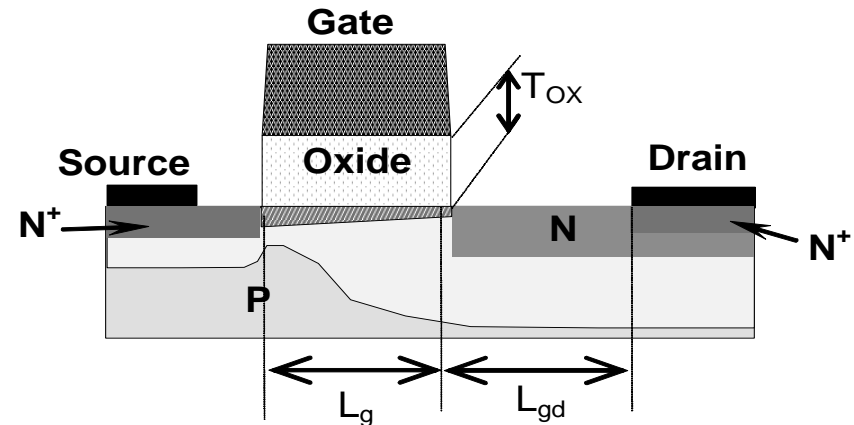
$$\frac{(P_{AC} + P_{DC})_{MIN}}{P_{IN}} = \frac{2 \cdot P_{AC}}{P_{IN}} \cong \left(\frac{V_{IN}}{V_{OUT}} \right) \left(\frac{S_{PWR}}{S_{DRV}} \right) F_0 K_D$$

- ✓ Stage Scaling (20, 50, 100...)
- ✓ K_D for CMOS ranges from 10ps to 100ps
- ✓ At 10MHz => for instance $F_0 \cdot K_D = 0.001$

Device / Process Optimization

[S. Ajram, G. Salmer, IEEE Trans. Power Electronics 2001]

| Parameter | Physics |
|--|--|
| Breakdown Voltage | $V_{dsB} \cong V_{dsuB} \cdot \left(\frac{1}{1+\beta} \right)^{\frac{1}{n}}$ |
| (V_{BD}) See Note (1) | $V_{dsuB} = 60 \cdot \left(\frac{E_g}{1.11} \right)^{\frac{3}{2}} \left(\frac{10^{16}}{N_A^{Channel}} \right)^{\frac{3}{4}}$ |
| On-State Resistance (R_{ON}) | $\frac{1}{q \cdot N_s^D \cdot \bar{\mu}_n^D} \cdot \frac{L_{gd}}{W_g}$ |
| Maximum Input Capacitance (C_{in}) | $W_g \cdot L_g \cdot C_{OX}$ |
| Loss Factor $k_D = C_{in} \cdot R_{ON}$ | $\frac{L_{gd} \cdot L_g \cdot C_{OX}}{q \cdot N_s^D \cdot \bar{\mu}_n^D}$ |



W_g : Gate width
 C_{OX} : Oxide capacitance
 V_{gsON} : Gate-to-source on-state voltage
 V_T : Threshold voltage
 N_sD, μ_nD : Respectively, the surface doping level and the electron mobility in the drain-to-channel lightly doped region
 $N_A^{Channel}$: Substrate doping level under the gate
 β : Parasitic substrate NPN transistor current gain
 v_s : Carrier saturation velocity

Note (1) Comment by Pr. Paul Chow, RPI USA
 This equation does not fit for bandgap larger than 2.5eV such as for SiC or GaN, use the following reference instead
 T. Paul Chow and Ritu Tyagi "Wide Bandgap Compound Semiconductors for Superior High-Voltage Unipolar Power Devices" IEEE TRANSACTIONS ON ELECTRON DEVICES, VOL. 41, NO. 8, AUGUST 1994

Process Optimization

1. Set Breakdown Voltage 1.8V, 5V etc...
2. Breakdown determines possible Doping
3. Doping Sets Mobility
4. Engineer L_g and T_{OX}
5. (Mobility + Doping + Gate) Sets Loss Factor

Slides to be requested

